Mechanical Aspects in Electronics Systems Design

By Vinay Divakar

GRIN Verlag Gmbh Aug 2014, 2014. Taschenbuch. Book Condition: Neu. 211x148x7 mm. This item is printed on demand - Print on Demand Neuware - Scientific Study from the year 2013 in the subject Engineering - Mechanical Engineering, grade: B+, , course: Electronics Systems Design, language: English, abstract: In chapter 1, the present research carried on the mature laser technology i.e. GaAs, in order to improve its efficiency. The packaging principle used for receivers can be applied for the packaging of the laser driver circuit and the laser source in a single module. The concept of FRACAS (Failure Reporting, Analysis and Corrective Action System) has been described and failure analysis technique for Electrical overstress (EOS) is described. An industrial approach to calculating the reliability of a system with some known data is described. Some challenges with respect to packaging has been discussed in detail and some methods to overcome challenges such as lattice mismatch has been described. Every electronic components or electronic systems have certain specifications based on which it is developed and all components have datasheets of their own. The datasheets consists complete details related to the product such as product design specifications, packaging type, power ratings, dimensions etc. Any...

Reviews

An extremely wonderful book with lucid and perfect information. It is one of the most awesome publication i have read. Your life period will probably be enhance the instant you total looking at this pdf.
-- ***Prof. Dan Windler MD***

It is really an amazing publication i actually have at any time read. It is really simplistic but unexpected situations inside the 50 percent of your pdf. Its been written in an exceptionally simple way in fact it is just right after i finished reading this ebook where actually transformed me, alter the way i really believe.
-- ***Dr. Celestino Spinka III***